**IMPACT-EMAP 2020**

**On-Demand Webinar Announcement**

**Sign up for 27 plenary/invited speeches videos on demand**

IMPACT-EMAP 2020 Conference, organized by IEEE-EPS-Taipei, iMAPS-Taiwan, ITRI and TPCA. For the past 15 years, IMPACT has been the global stage for innovation and one of the largest gathering of PCB and packaging professionals over the world. The theme of this year is “IMPACT-EMAP on HPC - Toward the Data Era.” The conference has reached more than 500 attendees participated in the physical conference during Oct 21st to 23rd.

It is fair to conclude that the conference was a great success! So many people have contributed in so many ways to turn this event into a smoothly running meeting with various intriguing presentations and posters; forming a very good atmosphere for discussion and networking. We thank our distinguished keynote speakers for their inspiring and timely insights. We also thank our TPC members for their wonderful response and continuing support. Most of all we wish to thank all of the participants, without whom, the success of the conference would not have been possible. All those who contributed to the conference: Thank you for all your excellent work!

Even though the physical conference of IMPACT-EMAP 2020 was concluded on Oct 23rd, the IMPACT-EMAP 2020 would like to make to maximize participation in order to engage with distinguished guest from around the world; a digital IMPACT-EMAP 2020 will allow the entire PCBs and packaging community to safely share ideas that will shape our future. You’ll be able to participate in all the awe-inspiring moments of IMPACT-EMAP 2020 with **27 videos of plenary/invited talks wherever you are in the world.** We are designing a unique experience for the tech industry.

**【Digital conference registration deadline】15th November, 2020.**

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| **Item** | **Price** |
| **Registration fee (Not including Proceeding)** | **NT$3,000** |
| **Digital Proceedings (Optional)** | **NT$3,000** |

**\*NO REFUND IS APPLICABLE when the On-Demand Webinar is started.\***

**【How to register?】Fill out the google form, or fill out the registration form and email to** register@impact.org.tw

**Video List**

**\*Video on-demand available from 16th to 30th November, 2020**

|  |  |  |  |  |
| --- | --- | --- | --- | --- |
| **No.** | **Session** | **Name** | **Affiliation** | **Topic** |
| 1 | Plenary | John Lau | Unimicron | Heterogeneous Integration for HPC Application Driven by AI and 5G |
| 2 | Plenary | Wenchi Ting | UMC | Emergent Memory Technology at the Crossroads |
| 3 | Plenary | David Chang | IBM Taiwan | Impact of Connected Manufacturing in the New 5G Era |
| 4 | 3D-Embedding | Yoshihisa Katoh　　 | Fukuoka University | Study of 3D Device Embedded Module toward the high-performance IoT Module and AI edge Module |
| 5 | 3D-Embedding | Chun-An Lu | ITRI | A New Material and Process Technology of Single Layer Embedded Capacitor |
| 6 | 3D-Embedding | Masaomi Suzuki | Zuken Inc. | System Level Co-Design Platform for 3D SiP & 3D electronic module |
| 7 | 3D-Embedding | Ray-Min Tain | Unimicron | Embedded Structure for PCB Thermal Solution in High Speed Optical Module |
| 8 | AI Technology | Emilie Jolivet | Yole Développement | AI processors : the new fuel of innovation in the advanced packaging industry |
| 9 | AI Technology | Nien-Ti Tsou | National Chiao Tung University | Preoperative Evaluations of Dental Implants and Bone Healing Prediction by Deep Learning Network |
| 10 | Heterogeneous Integration 1 | Daniel Chang | TSMC | Heterogeneous System-Level Package Integration – Trends and Challenges |
| 11 | Heterogeneous Integration 1 | Jan Vardaman | TechSearch | Future applications and markets for Heterogeneous Integration |
| 12 | Heterogeneous Integration 2 | C. Key Chung | SPIL | Advanced Packaging Solutions for High Performance Computing and Big Data processing |
| 13 | Heterogeneous Integration 2 | Rozalia Beica | AT&S | Driving Future Innovation and Growth through Heterogeneous Integration |
| 14 | Heterogeneous Integration 2 | Chuan-Seng Tan | Nanyang Technology University | Heterogeneous Integration of Surface Ion Trap, Silicon Photonics and 3D-TSV for Quantum Computing |
| 15 | HPC | Jan Vardaman | TechSearch | HPC options and challenges |
| 16 | HPC | Jobert van Eisden & Sven Lamprecht | Atotech | Process technology evolution to enable more than Moore system scaling in High performance computing |
| 17 | ICEP | Takashi Hisada | IBM Research Tokyo | AI Hardware Drives Innovation of Heterogeneous Integration |
| 18 | ICEP | Atsushi Takahashi | NAGASE & CO., LTD. | Market Trend of FOPLP |
| 19 | ICEP | Satoru Kuramochi | Dai Nippon Printing Co., Ltd. | High Frequency Chracteristics of Glass Interposer |
| 20 | ICEP | Tomoaki Shibata | Hitachi Chemical Co., Ltd. | Fabrication of Imprint-Through Mold Via (i-TMV) and its application for compartmental EMI shielding |
| 21 | JIEP | Yasuyuki SAKAMOTO | Toray Engineering Co., Ltd. | Total Solutions for mass production of micro LED display |
| 22 | JIEP | Po Chao Chang | Sekisui Chemical(Taiwan) Co.,Ltd. | Dielectric Material with Low Insertion Loss at High Operational Temperature Enabling Features for Next-Gen 2.5D Packages for HPC |
| 23 | JIEP | Iori DOI | Mitsubishi Chemical Corporation | Development of Highly Flexible/Stretchable Epoxy Film, Especially Suitable for Display and Printed Electronics |
| 24 | JIEP | Yu Shoji | Toray Industries, Inc. | Low Stress and Low Temperature Curable Photosensitive Polyimide |
| 25 | SiP | Santosh Kumar | Yole Développement | System in Package (SiP) business is booming driven by heterogeneous integration demand |
| 26 | SiP | Andreas Ostmann  | Fraunhofer IZM | PCB Frame Embedding for High-Density Packages |
| 27 | SiP | Chih Yuan Shih | SPIL | Innovative Antenna in Package Solution for 5G mmW |

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**IMPACT-EMAP 2020 -On-Demand Webinar Registration Form**

**【On-Demand Webinar Registration Deadline】15th November, 2020**

**General Information**

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| Full Name |  | Nationality |  |
| Company/ School Affiliation |  | Email  |  |
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| Purchasing Item | **( )** **On-Demand Webinar :NTD3,000****( ) Digital Proceedings: NTD3,000** |
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